Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.129”**

**PAD FUNCTION:**

1. **GND**

**.015”**

**ANODE**

**.005”**

**.015”**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .005”**

**Backside Potential: CATHODE**

**Mask Ref: BKC**

**APPROVED BY: DK DIE SIZE .015” X .015” DATE: 10/21/21**

**MFG: ALLEGRO / SPRAGUE THICKNESS .007” P/N: 1N3070**

**DG 10.1.2**

#### Rev B, 7/1